

HMHAA280, HMHA2801 Series, HMHA281 Half Pitch Mini-Flat Package 4-Pin Optocouplers

Features

- Compact 4-pin package (2.4mm maximum standoff height)
- Half pitch leads for optimum board space savings
- Current Transfer Ratio in selected groups

HMHA2801: 80–600%	HMHA2801A: 80–160%
HMHA2801B: 50–150%	HMHA2801C: 50–100%
HMHA281: 50–600%	HMHAA280: 50–600%
- Available in tape and reel quantities of 500 and 2500
- Applicable to Infrared Ray reflow (230°C Max, 30 seconds)
- BSI (File #8611/8612), CSA (File #1201524), UL (File #E90700) and VDE (File #136480) certified

Description

The HMHA281, HMHA2801 Series consists of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a compact 4-pin mini-flat package. The lead pitch is 1.27mm.

The HMHAA280 series consists of two gallium arsenide infrared emitting diodes, connected in inverse parallel, driving a single silicon phototransistor in a compact 4-pin mini-flat package. The lead pitch is 1.27mm.

Applications

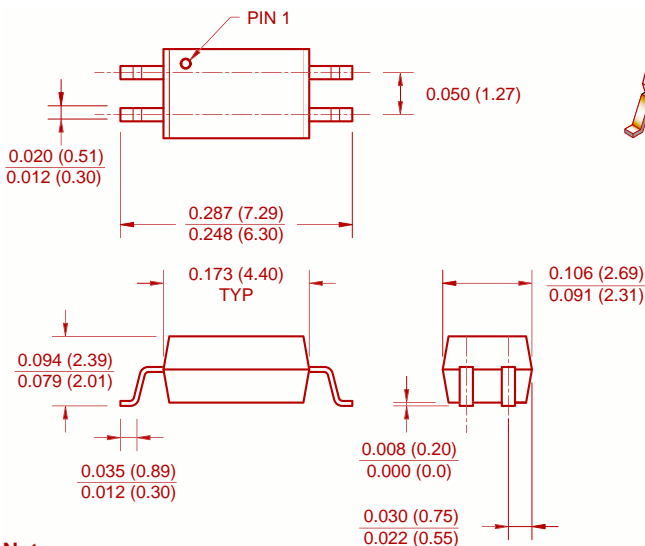
HMHAA280

- AC line monitor
- Unknown polarity DC sensor
- Telephone line receiver

HMHA281, HMHA2801 Series

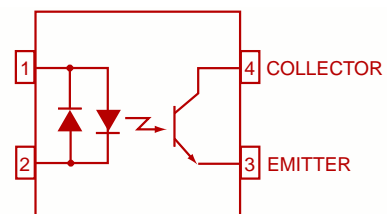
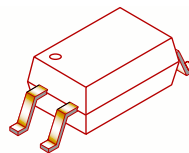
- Digital logic inputs
- Microprocessor inputs
- Power supply monitor
- Twisted pair line receiver
- Telephone line receiver

Package Dimensions

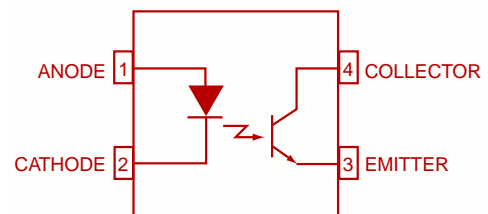


Note:

All dimensions are in inches (millimeters)



Equivalent Circuit
(HMHAA280)



Equivalent Circuit
(HMHA281, HMHA2801)

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
TOTAL PACKAGE			
T_{STG}	Storage Temperature	-55 to +125	$^\circ\text{C}$
T_{OPR}	Operating Temperature	-55 to +100	$^\circ\text{C}$
EMITTER			
$I_{\text{F (avg)}}$	Continuous Forward Current	50	mA
$I_{\text{F (pk)}}$	Peak Forward Current (1 μs pulse, 300pps.)	1	A
V_{R}	Reverse Input Voltage (HMHA)	6	V
P_{D}	Power Dissipation	60	mW
	Derate linearly (above 25°C)	0.6	mW/ $^\circ\text{C}$
DETECTOR			
	Continuous Collector Current	50	mA
P_{D}	Power Dissipation	150	mW
	Derate linearly (above 25°C)	1.5	mW/ $^\circ\text{C}$
V_{CEO}	Collector-Emitter Voltage	80	V
V_{ECO}	Emitter-Collector Voltage	7	V

Electrical Characteristics ($T_A = 25^\circ\text{C}$)

Symbol	Parameter	Test Conditions	Device	Min.	Typ.*	Max.	Unit
INDIVIDUAL COMPONENT CHARACTERISTICS							
Emitter							
V_{F}	FF (pkV)						



Typical Performance Characteristics

Fig. 1 Forward Current vs. Forward Voltage

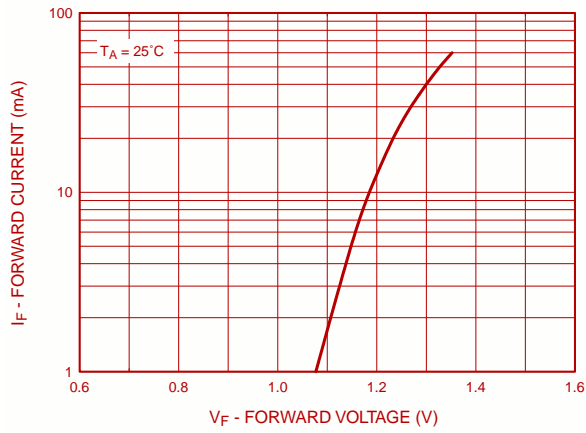


Fig. 2 Collector Current vs. Forward Current

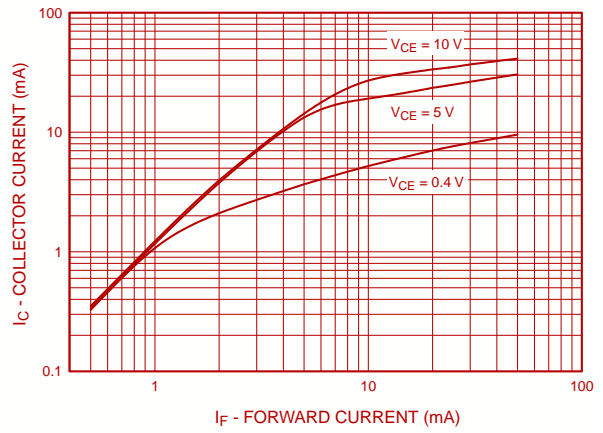


Fig. 3 Current Transfer Ratio vs. Forward Current

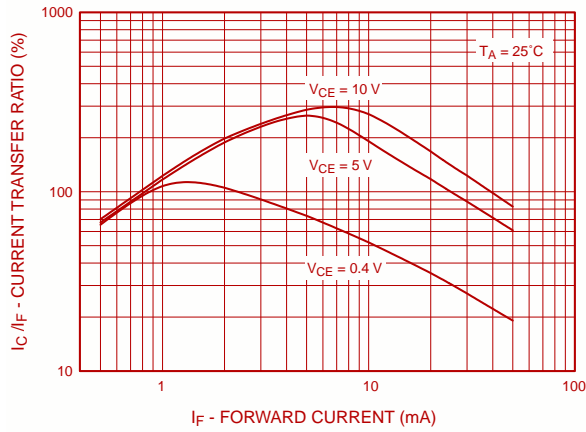


Fig. 4 Normalized CTR vs. Temperature

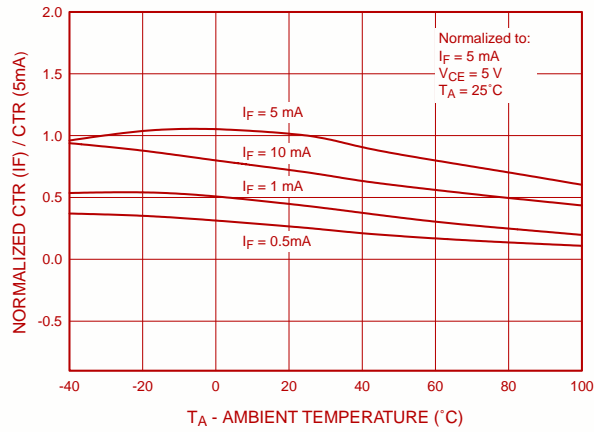
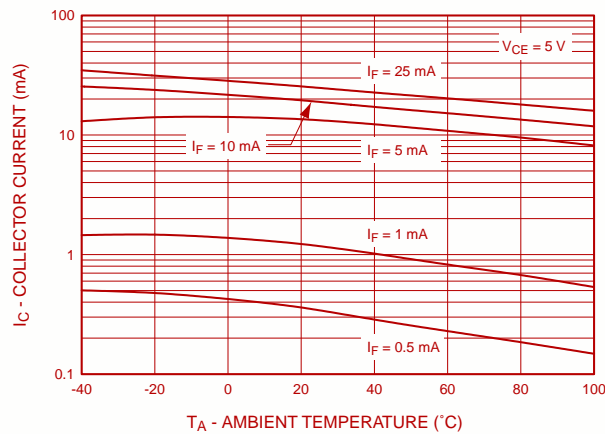


Fig. 5 Collector Current vs. Temperature



Typical Performance Characteristics (Continued)

Fig. 6 Collector Current vs. Collector-Emitter Voltage

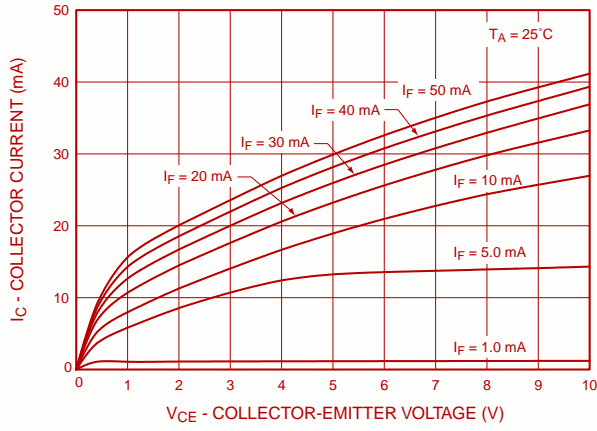


Fig. 7 Collector Current vs. Collector-Emitter Voltage

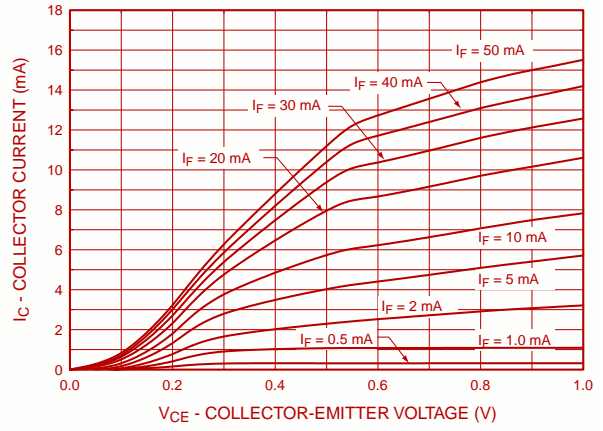


Fig. 8 Collector Dark Current vs. Temperature

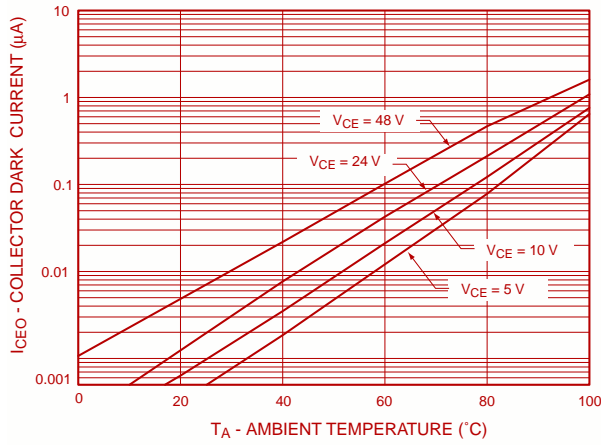


Fig. 9 Switching Time vs. Load Resistance

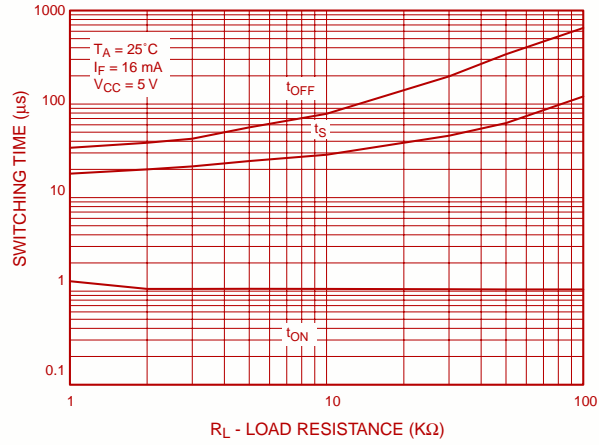
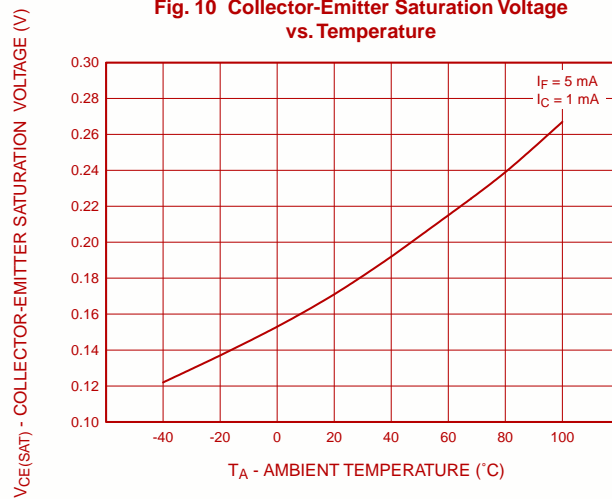


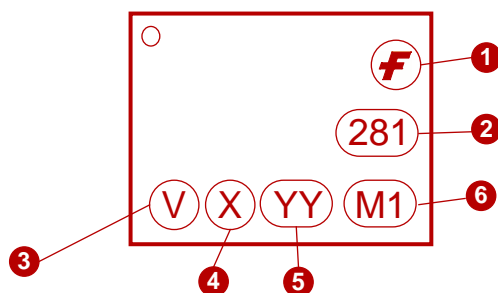
Fig. 10 Collector-Emitter Saturation Voltage vs. Temperature



Ordering Information

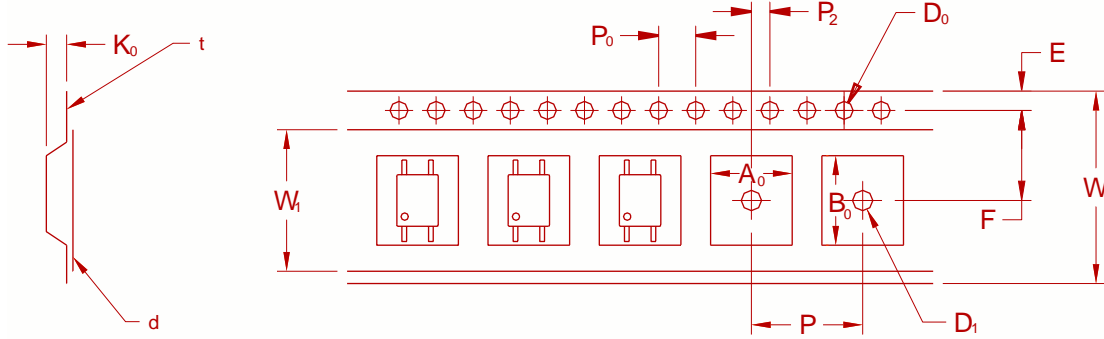
Option	Description
V	VDE Approved
R1	Tape and Reel (500 units)
R2	Tape and Reel (2500 units)
R3	Tape and Reel (500 units; unit 180° rotated)
R4	Tape and Reel (2500 units; unit 180° rotated)
R1V	Tape and Reel (500 units) and VDE Approved
R2V	Tape and Reel (2500 units) and VDE Approved
R3V	Tape and Reel (500 units; unit 180° rotated) and VDE Approved
R4V	Tape and Reel (2500 units; unit 180° rotated) and VDE Approved

Marking Information



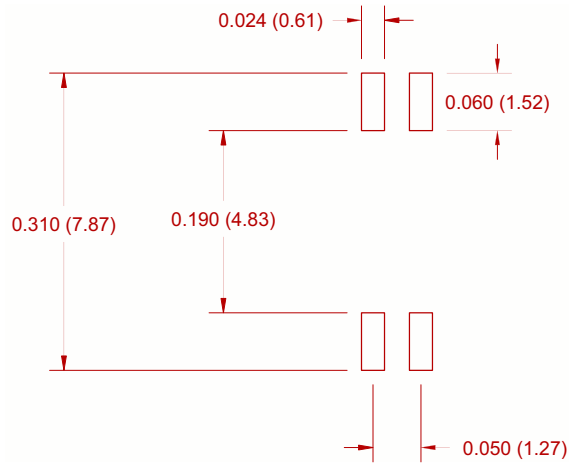
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

Tape and Reel Dimensions

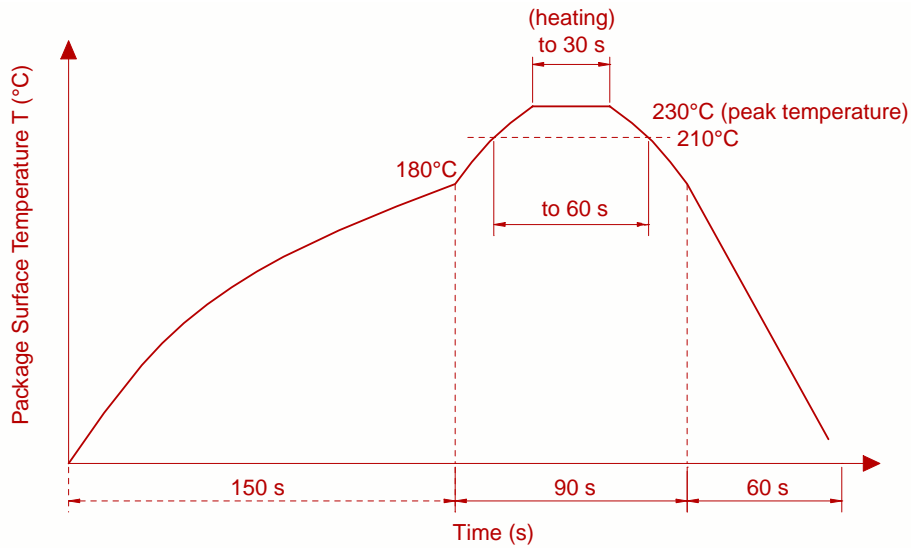


Description		Symbol	1.27 Pitch Dimensions (mm)
Tape Width		W	12.00±0.4
Tape Thickness		t	0.30±0.20
Sprocket Hole Pitch		P ₀	4.00±0.20
Sprocket Hole Dia.		D ₀	1.55±0.20
Sprocket Hole Location		E	1.75±0.20
Pocket Location		F	5.50±0.20
		P ₂	2.00±0.20
Pocket Pitch		P	8.00±0.20
Pocket Dimension		A ₀	4.40±0.20
		B ₀	7.30±0.20
		K ₀	2.30±0.20
Pocket Hole Dia.		D ₁	1.55±0.20
Cover Tape Width		W ₁	9.20
Cover Tape Thickness		d	0.065±0.02
Max. Component Rotation or Tilt			20° max
Devices Per Reel		R1	500
		R2	2500
Reel Diameter		R1	178 mm (7")
		R2	330 mm (13")

Footprint Drawing for PCB Layout



Recommended Infrared Reflow Soldering Profile



- Peak reflow temperature: 230°C (package surface temperature) for 30 seconds
- Time of temperature higher than 210°C: 60 seconds or less
- One time soldering reflow is recommended

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Build it Now™	FRFET™	MicroFET™	QFET®	SuperSOT™-8
CoolFET™	GlobalOptoisolator™	MicroPak™	QS™	SyncFET™
CROSSVOLT™	GTO™	MICROWIRE™	QT Optoelectronics™	TCM™
DOME™	HiSeC™	MSX™	Quiet Series™	TinyLogic®
EcoSPARK™	I ² C™	MSXPro™	RapidConfigure™	TINYOPTO™
E ² CMOS™	i-Lo™	OCX™	RapidConnect™	TruTranslation™
EnSigna™	ImpliedDisconnect™	OCXPro™	μSerDes™	UHC™
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FACT Quiet Series™		OPTOPLANAR™	SILENT SWITCHER®	UltraFET®
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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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